

forming a p transistor and an n transistor in the heterostructure, wherein the strained layer comprises a channel of at least one of the transistors, the transistors being interconnected in a CMOS circuit.

6 ⁵ 35. The method of claim ⁵ 32 wherein the heterostructure further comprises an insulating layer below the strained layer.

D6 7 ^{15 5} 34. The method of claim ^{15 5} 32 wherein the heterostructure further comprises a SiGe graded buffer layer positioned between the relaxed Si_{1-x}Ge_x layer and the Si substrate.

8 ⁵ 35. The method of claim ⁵ 32 wherein the strained layer comprises Si.

9 ⁵ 36. The method of claim ⁵ 32 wherein $0.1 < x < 0.5$.

10 ⁵ 37. The method of claim ⁵ 32 wherein the CMOS circuit comprises a logic gate.

11 ¹⁰ 38. The method of claim ¹⁰ 37 wherein the logic gate is a NOR gate.